

LISTING OF CLAIMS

29. (Previously presented) A radio frequency (RF) component comprising:
a dielectric layer having opposing first and second major surfaces, the first surface being free from a semiconductor substrate, said dielectric layer having a plurality of openings extending between the first and second opposing major surfaces; and
a patterned conductive layer on the second major surface of said dielectric layer,
wherein the plurality of openings are arranged in a predetermined pattern along laterally opposing sides of the patterned conductive layer.

30-33 (Canceled)

34. (Previously presented) The radio frequency (RF) component of Claim 29, wherein each of the openings has respective rounded over edges adjacent the first and second major surfaces.

35. (Previously presented) The RF component of Claim 29 wherein the plurality of openings are laterally adjacent portions of the patterned conductive layer with no openings extending through the patterned conductive layer.

36. (Original) The RF component of Claim 29, wherein each of the plurality of openings are cylindrically shaped.

37. (Original) The RF component of Claim 29, wherein there is substantially uniform spacing between the adjacent openings on each of the opposing sides of the patterned conductive layer.

38. (Original) The RF component of Claim 37, wherein the substantially uniform spacing between the adjacent openings ranges from about 20 to about 200 μm .

39. (Original) The RF component of Claim 29, wherein each of the openings has a diameter in a range of about 0.5 to 20 μm .

40. (Original) The RF component of Claim 29, wherein the patterned conductive layer does not intervene between the adjacent openings along each of the laterally opposing sides.